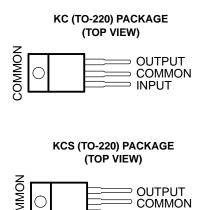


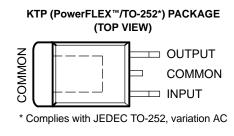
#### **FEATURES**

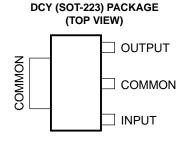
- 3-Terminal Regulators
- Output Current up to 500 mA
- No External Components
- Internal Thermal-Overload Protection



**INPUT** 

- High Power-Dissipation Capability
- Internal Short-Circuit Current Limiting
- Output Transistor Safe-Area Compensation





#### **DESCRIPTION/ORDERING INFORMATION**

This series of fixed-voltage integrated-circuit voltage regulators is designed for a wide range of applications. These applications include on-card regulation for elimination of noise and distribution problems associated with single-point regulation. Each of these regulators can deliver up to 500 mA of output current. The internal current-limiting and thermal-shutdown features of these regulators essentially make them immune to overload. In addition to use as fixed-voltage regulators, these devices can be used with external components to obtain adjustable output voltages and currents and also as the power-pass element in precision regulators.

Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

PowerFLEX, PowerPAD are trademarks of Texas Instruments.

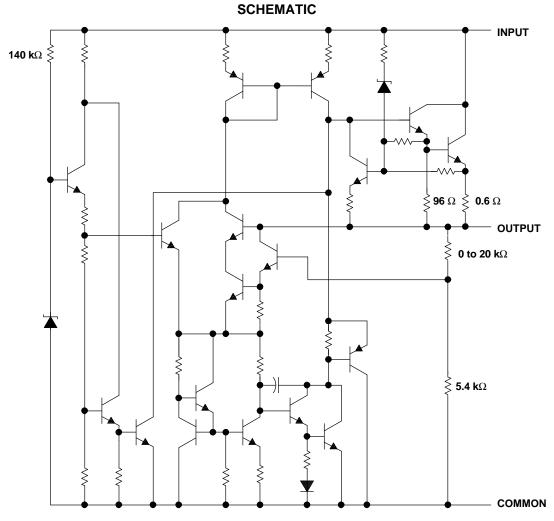


#### **ORDERING INFORMATION**

T <sub>A</sub>	V <sub>O</sub> (NOM) (V)	PACKAGE <sup>(1)</sup>		ORDERABLE PART NUMBER	TOP-SIDE MARKING
		PowerFLEX <sup>™</sup> /TO-252 <sup>(2)</sup> – KTP	Reel of 3000	μΑ78M33CKTPR	UA78M33C
	3.3	SOT-223 – DCY	Tube of 80	μA78M33CDCY	C3
	3.3	SO1-223 - DC1	Reel of 2500	μA78M33CDCYR	- 03
		TO-220 – KC	Tube of 50	μΑ78М33СКС	UA78M33C
		PowerFLEX/TO-252 <sup>(2)</sup> – KTP	Reel of 3000	μΑ78M05CKTPR	UA78M05C
		SOT-223 – DCY	Tube of 80	μΑ78M05CDCY	C5
	5	301-223 - DC1	Reel of 2500	μΑ78M05CDCYR	CS
		TO-220 – KC	Tube of 50	μA78M05CKC	UA78M05C
0°C to 125°C		TO-220, short shoulder – KCS	Tube of 20	μA78M05CKCS	UA/6IVIUSC
0 C to 125 C	6	PowerFLEX/TO-252 <sup>(2)</sup> – KTP	Reel of 3000	μΑ78M06CKTPR	UA78M06C
		PowerFLEX/TO-252 <sup>(2)</sup> – KTP	Reel of 3000	μΑ78M08CKTPR	UA78M08C
	8	SOT-223 – DCY	Tube of 80	μΑ78M08CDCY	C8
	0	301-223 - DC1	Reel of 2500	μΑ78M08CDCYR	Co
		TO-220 – KC	Tube of 50	μΑ78M08CKC	UA78M08C
	9	PowerFLEX/TO-252 <sup>(2)</sup> – KTP	Reel of 3000	μΑ78M09CKTPR	UA78M09C
	10	PowerFLEX/TO-252 <sup>(2)</sup> – KTP	Reel of 3000	μΑ78M10CKTPR	UA78M10C
	12	PowerFLEX/TO-252 <sup>(2)</sup> – KTP	Reel of 3000	μΑ78M12CKTPR	UA78M12C
	12	TO-220 – KC	Tube of 50	μΑ78M12CKC	UA78M12C
		PowerFLEX/TO-252 <sup>(2)</sup> – KTP	Reel of 3000	μΑ78M05IKTPR	UA78M05I
		SOT-223 – DCY	Tube of 80	μΑ78M05IDCY	- J5
–40°C to 125°C	5	301-223 - DC1	Reel of 2500	μΑ78M05IDCYR	33
		TO-220 – KC	Tube of 50	μΑ78M05IKC	UA78M05I
		TO-220, short shoulder – KCS	Tube of 20	μΑ78M05IKCS	OA7 OIVIUSI

 <sup>(1)</sup> Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.
 (2) Complies with JEDEC TO-252, variation AC





Resistor values shown are nominal.

# μΑ78M00 SERIES POSITIVE-VOLTAGE REGULATORS





#### Absolute Maximum Ratings<sup>(1)</sup>

over virtual junction temperature range (unless otherwise noted)

		MIN	MAX	UNIT
$V_{I}$	Input voltage		35	V
$T_{J}$	Operating virtual junction temperature		150	°C
T <sub>stq</sub>	Storage temperature range	-65	150	°C

<sup>(1)</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

#### Package Thermal Data<sup>(1)</sup>

PACKAGE	BOARD	θ <sub>JP</sub> <sup>(2)</sup>	θјС	$\theta_{JA}$
PowerFLEX/TO-252 - KTP	High K, JESD 51-5	1.4°C/W	19°C/W	28°C/W
SOT-223 - DCY	High K, JESD 51-7		30.6°C/W	53°C/W
TO-220 - KC/KCS	High K, JESD 51-5	3°C/W	17°C/W	19°C/W

<sup>(1)</sup> Maximum power dissipation is a function of  $T_J(max)$ ,  $\theta_{JA}$ , and  $T_A$ . The maximum allowable power dissipation at any allowable ambient temperature is  $P_D = (T_J(max) - T_A)/\theta_{JA}$ . Operating at the absolute maximum  $T_J$  of 150°C can affect reliability.

#### **Recommended Operating Conditions**

			MIN	MAX	UNIT
		μΑ78Μ33	5.3	25	
		μΑ78Μ05	7	25	
		μΑ78Μ06	8	25	
\/	Input valtage	μΑ78Μ08	10.5	25	V
VI	Input voltage	μΑ78Μ09	11.5	26	V
		μΑ78Μ10	12.5	28	
		μA78M12	14.5	30	
		μA78M15	17.5	30	
Io	Output current			500	mA
т	Operating virtual junction temporature	μΑ78MxxC	0	125	°C
TJ	Operating virtual junction temperature	μΑ78MxxI	-40	125	٠.

<sup>(2)</sup> For packages with exposed thermal pads, such as QFN, PowerPAD™, or PowerFLEX, θ<sub>JP</sub> is defined as the thermal resistance between the die junction and the bottom of the exposed pad.

SLVS059P-JUNE 1976-REVISED OCTOBER 2005

#### **Electrical Characteristics**

at specified virtual junction temperature,  $V_I = 8 \text{ V}$ ,  $I_O = 350 \text{ mA}$ ,  $T_J = 25^{\circ}\text{C}$  (unless otherwise noted)

PARAMETER	TEST CONDITIONS <sup>(1)</sup>			μ <b>Α78Μ33C</b>			
PARAMETER	IES	TEST CONDITIONS (7)			MAX	UNIT	
Output voltage (2)	I <sub>O</sub> = 5 mA to 350 mA,		3.2	3.3	3.4	V	
Output voltage <sup>(2)</sup>	$V_1 = 8 \text{ V to } 20 \text{ V}$	$T_J = 0$ °C to 125°C	3.1	3.3	3.5	V	
Input voltage regulation	1 - 200 mA	V <sub>I</sub> = 5.3 V to 25 V		9	100	m\/	
Input voltage regulation	$I_0 = 200 \text{ mA}$	V <sub>I</sub> = 8 V to 25 V		3	50	mV	
Ripple rejection	$V_{I} = 8 \text{ V to } 18 \text{ V},$	$I_{O} = 100 \text{ mA}, T_{J} = 0^{\circ}\text{C to } 125^{\circ}\text{C}$	62			.ID	
	f = 120 Hz	I <sub>O</sub> = 300 mA	62	80		dB	
Output voltage regulation	V <sub>I</sub> = 8 V,	I <sub>O</sub> = 5 mA to 500 mA		20	100	mV	
Temperature coefficient of output voltage	I <sub>O</sub> = 5 mA,	T <sub>J</sub> = 0°C to 125°C		-1		mV/°C	
Output noise voltage	f = 10 Hz to 100 kHz			40	200	μV	
Dropout voltage				2		V	
Bias current				4.5	6	mA	
Diag surrent change	$I_O = 200 \text{ mA}, V_I = 8 \text{ V to } 25$	$V, T_J = 0$ °C to 125°C			0.8	A	
Bias current change	$I_O = 5$ mA to 350 mA,	$T_J = 0$ °C to 125°C			0.5	mA	
Short-circuit output current	V <sub>I</sub> = 35 V			300		mA	
Peak output current				700		mA	

All characteristics are measured with a 0.33-µF capacitor across the input and a 0.1-µF capacitor across the output. Pulse-testing techniques maintain  $T_J$  as close to  $T_A$  as possible. Thermal effects must be taken into account separately. This specification applies only for dc power dissipation permitted by absolute maximum ratings

#### **Electrical Characteristics**

at specified virtual junction temperature,  $V_I = 10 \text{ V}$ ,  $I_O = 350 \text{ mA}$ ,  $T_J = 25^{\circ}\text{C}$  (unless otherwise noted)

DADAMETED	TEST CONDITIONS <sup>(1)</sup>		μ <b>Α78Μ05C</b>			LINUT	
PARAMETER	IES	TEST CONDITIONS.			MAX	UNIT	
Output voltage	I <sub>O</sub> = 5 mA to 350 mA,		4.8	5	5.2	V	
Output voltage	$V_I = 7 \text{ V to } 20 \text{ V}$	$T_J = 0$ °C to 125°C	4.75		5.25	V	
Input voltage regulation	I <sub>O</sub> = 200 mA	V <sub>I</sub> = 7 V to 25 V		3	100	mV	
Input voltage regulation	1 <sub>0</sub> = 200 IIIA	V <sub>I</sub> = 8 V to 25 V		1	50	IIIV	
Pinnla raigation	V <sub>I</sub> = 8 V to 18 V,	$I_{O} = 100 \text{ mA}, T_{J} = 0^{\circ}\text{C to } 125^{\circ}\text{C}$	62			٩D	
Ripple rejection	f = 120 Hz	I <sub>O</sub> = 300 mA	62	80		dB	
Output voltage regulation	I <sub>O</sub> = 5 mA to 500 mA			20	100	mV	
	$I_O = 5$ mA to 200 mA	O = 5 mA to 200 mA		10	50	IIIV	
Temperature coefficient of output voltage	I <sub>O</sub> = 5 mA,	$T_J = 0$ °C to 125°C		-1		mV/°C	
Output noise voltage	f = 10 Hz to 100 kHz			40	200	μV	
Dropout voltage				2		V	
Bias current				4.5	6	mA	
Diag current change	$I_O = 200 \text{ mA}, V_I = 8 \text{ V to } 25$	V, $T_J = 0^{\circ}C$ to 125°C			0.8	A	
Bias current change	$I_0 = 5 \text{ mA to } 350 \text{ mA},$	$T_J = 0$ °C to 125°C			0.5	mA	
Short-circuit output current	V <sub>I</sub> = 35 V			300		mA	
Peak output current				0.7		Α	

<sup>(1)</sup> All characteristics are measured with a 0.33-μF capacitor across the input and a 0.1-μF capacitor across the output. Pulse-testing techniques maintain T<sub>J</sub> as close to T<sub>A</sub> as possible. Thermal effects must be taken into account separately.



#### **Electrical Characteristics**

at specified virtual junction temperature,  $V_I = 10 \text{ V}$ ,  $I_O = 350 \text{ mA}$ ,  $T_J = 25^{\circ}\text{C}$  (unless otherwise noted)

PARAMETER	TEST CONDITIONS <sup>(1)</sup>		μ	μ <b>Α78M05I</b>			
PARAMETER	'	EST CONDITIONS(*)	MIN	TYP	MAX	UNIT	
Output valtage	$I_O$ = 5 mA to 350 mA, $V_I$ = 7 V to 20 V		4.8	5	5.2	V	
Output voltage		$T_J = -40^{\circ}\text{C} \text{ to } 125^{\circ}\text{C}$	4.75		5.25	V	
Input valtage regulation	1 200 mA	V <sub>I</sub> = 7 V to 25 V		3	100	mV	
Input voltage regulation	I <sub>O</sub> = 200 mA	V <sub>I</sub> = 8 V to 25 V		1	50	IIIV	
Ripple rejection	V <sub>I</sub> = 8 V to 18 V,	$I_{O} = 100 \text{ mA}, T_{J} = -40^{\circ}\text{C to } 125^{\circ}\text{C}$	62			J.	
	f = 120 Hz	I <sub>O</sub> = 300 mA	62	80		dB	
Outside all and an analysis a	I <sub>O</sub> = 5 mA to 500 mA			20	100	\/	
Output voltage regulation	I <sub>O</sub> = 5 mA to 200 mA			10	50	mV	
Temperature coefficient of output voltage	I <sub>O</sub> = 5 mA,	$T_{J} = -40^{\circ}\text{C} \text{ to } 125^{\circ}\text{C}$		-1		mV/°C	
Output noise voltage	f = 10 Hz to 100 kHz			40	200	μV	
Dropout voltage				2		V	
Bias current				4.5	6	mA	
Dies sument shares	$I_0 = 200 \text{ mA}, V_1 = 8 \text{ V to } 200 \text{ mA}$	25 V, T <sub>J</sub> = -40°C to 125°C			0.8	mA	
Bias current change	$I_{O} = 5 \text{ mA to } 350 \text{ mA},$	$T_J = -40^{\circ}\text{C} \text{ to } 125^{\circ}\text{C}$			0.5		
Short-circuit output current	V <sub>I</sub> = 35 V			300		mA	
Peak output current				0.7		Α	

<sup>(1)</sup> All characteristics are measured with a  $0.33-\mu F$  capacitor across the input and a  $0.1-\mu F$  capacitor across the output. Pulse-testing techniques maintain  $T_J$  as close to  $T_A$  as possible. Thermal effects must be taken into account separately.

#### **Electrical Characteristics**

at specified virtual junction temperature,  $V_I$  = 11 V,  $I_O$  = 350 mA,  $T_J$  = 25°C (unless otherwise noted)

PARAMETER	TEST CONDITIONS <sup>(1)</sup>			μ <b>Α</b>	μ <b>Α78Μ06C</b>		
PARAMETER	TEST CONDITIONS.				TYP	MAX	UNIT
Output voltage	L = 5 mΛ to 250 mΛ	\/ - 9 \/ +0 21 \/		5.75	6	6.25 V	V
Output voltage	$I_0 = 5 \text{ mA to } 350 \text{ mA},$	$V_1 = 8 \text{ V to } 21 \text{ V}$	$T_J = 0$ °C to 125°C	5.7		6.3	V
Input voltage regulation	1 200 m A	$V_{I} = 8 \text{ V to } 25 \text{ V}$			5	100	mV
input voltage regulation	I <sub>O</sub> = 200 mA	$V_{I} = 9 \text{ V to } 25 \text{ V}$			1.5	50	IIIV
Ripple rejection	V <sub>I</sub> = 8 V to 18 V,	f = 120 Hz	$I_{O} = 100 \text{ mA},$ $T_{J} = 0^{\circ}\text{C to } 125^{\circ}\text{C}$	59			dB
	•		I <sub>O</sub> = 300 mA	59	80		
Output voltage regulation	$I_O = 5$ mA to 500 mA				20	120	mV
Output voltage regulation	$I_O = 5$ mA to 200 mA				10	60	IIIV
Temperature coefficient of output voltage	I <sub>O</sub> = 5 mA,	$T_J = 0$ °C to 125°C			-1		mV/°C
Output noise voltage	f = 10 Hz to 100 kHz				45		μV
Dropout voltage					2		V
Bias current					4.5	6	mA
Diag gurrant change	$V_{I} = 9 V \text{ to } 25 V,$	$I_0 = 200 \text{ mA},$	$T_J = 0^{\circ}C$ to $125^{\circ}C$			0.8	A
Bias current change	$I_{O} = 5 \text{ mA to } 350 \text{ mA},$	$T_J = 0$ °C to 125°C				0.5	mA
Short-circuit output current	V <sub>I</sub> = 35 V				270		mA
Peak output current					0.7		Α

<sup>(1)</sup> All characteristics are measured with a  $0.33-\mu F$  capacitor across the input and a  $0.1-\mu F$  capacitor across the output. Pulse-testing techniques maintain  $T_J$  as close to  $T_A$  as possible. Thermal effects must be taken into account separately.



#### **Electrical Characteristics**

at specified virtual junction temperature,  $V_I = 14 \text{ V}$ ,  $I_O = 350 \text{ mA}$ ,  $T_J = 25^{\circ}\text{C}$  (unless otherwise noted)

DADAMETER	TEST CONDITIONS <sup>(1)</sup>			μ <b>Δ</b>	μ <b>Α78Μ08C</b>		
PARAMETER	TEST CONDITIONS				TYP	MAX	UNIT
Output voltage	$V_1 = 10.5 \text{ V to } 23 \text{ V},$	I − Ε mΛ to 2Ε0 mΛ		7.7	8	8.3	V
Output voltage	V <sub>1</sub> = 10.5 V to 25 V,	$I_O = 5 \text{ mA to } 350 \text{ mA}$	$T_J = 0$ °C to 125°C	7.6		8.4	٧
Input voltage regulation	I <sub>O</sub> = 200 mA	$V_I = 10.5 \text{ V to } 25 \text{ V}$			6	100	mV
	1 <sub>0</sub> = 200 IIIA	$V_{I} = 11 \text{ V to } 25 \text{ V}$			2	50	IIIV
Dinale rejection	$V_I = 11 \text{ V to } 21.5 \text{ V},$	$I_{O} = 100 \text{ mA},$	$T_J = 0^{\circ}C$ to $125^{\circ}C$	56			dB
Ripple rejection	f = 120 Hz	I <sub>O</sub> = 300 mA		56	80		uБ
Output voltage regulation	I <sub>O</sub> = 5 mA to 500 mA				25	160	mV
	I <sub>O</sub> = 5 mA to 200 mA				10	80	IIIV
Temperature coefficient of output voltage	I <sub>O</sub> = 5 mA,	$T_J = 0^{\circ}\text{C} \text{ to } 125^{\circ}\text{C}$			-1		mV/°C
Output noise voltage	f = 10 Hz to 100 kHz				52		μV
Dropout voltage					2		V
Bias current					4.6	6	mA
Diag gurrant abanga	V <sub>I</sub> = 10.5 V to 25 V,	I <sub>O</sub> = 200 mA,	$T_J = 0$ °C to 125°C			0.8	A
Bias current change	$I_{O} = 5 \text{ mA to } 350 \text{ mA},$	$T_J = 0^{\circ}C$ to $125^{\circ}C$				0.5	mA
Short-circuit output current	V <sub>I</sub> = 35 V				250		mA
Peak output current					0.7		Α

<sup>(1)</sup> All characteristics are measured with a 0.33-μF capacitor across the input and a 0.1-μF capacitor across the output. Pulse-testing techniques maintain T<sub>J</sub> as close to T<sub>A</sub> as possible. Thermal effects must be taken into account separately.

#### **Electrical Characteristics**

at specified virtual junction temperature,  $V_I = 16 \text{ V}$ ,  $I_O = 350 \text{ mA}$ ,  $T_J = 25^{\circ}\text{C}$  (unless otherwise noted)

PARAMETER	TEST CONDITIONS <sup>(1)</sup>			μ <b>Α</b>	μ <b>Α78Μ09C</b>		
PARAMETER	TEST CONDITIONS(**)				TYP	MAX	UNIT
Output voltage	\/ - 11 5 \/ +0 24 \/	L = Ε m Λ to 250 m Λ		8.6	9	9.4	V
Output voltage	$V_{I} = 11.5 \text{ V to } 24 \text{ V},$	$I_O = 5 \text{ mA to } 350 \text{ mA}$	$T_J = 0$ °C to 125°C	8.5		9.5	V
Input voltage regulation	1 200 m A	$V_I = 11.5 \text{ V to } 26 \text{ V}$			6	100	mV
	I <sub>O</sub> = 200 mA	V <sub>I</sub> = 12 V to 26 V			2	50	IIIV
Dinale rejection	V <sub>I</sub> = 13 V to 23 V,	I <sub>O</sub> = 100 mA,	$T_J = 0$ °C to 125°C	56			dB
Ripple rejection	f = 120 Hz	I <sub>O</sub> = 300 mA		56	80		ав
Output voltage regulation	I <sub>O</sub> = 5 mA to 500 mA				25	180	mV
	I <sub>O</sub> = 5 mA to 200 mA				10	90	IIIV
Temperature coefficient of output voltage	I <sub>O</sub> = 5 mA,	$T_J = 0^{\circ}C$ to 125°C			-1		mV/°C
Output noise voltage	f = 10 Hz to 100 kHz				58		μV
Dropout voltage					2		V
Bias current					4.6	6	mA
Dian assessed about	$V_I = 11.5 \text{ V to } 26 \text{ V},$	I <sub>O</sub> = 200 mA,	$T_J = 0$ °C to 125°C			0.8	A
Bias current change	$I_{O} = 5 \text{ mA to } 350 \text{ mA},$	$T_J = 0$ °C to 125°C				0.5	mA
Short-circuit output current	V <sub>I</sub> = 35 V				250		mA
Peak output current					0.7		Α

<sup>(1)</sup> All characteristics are measured with a  $0.33-\mu F$  capacitor across the input and a  $0.1-\mu F$  capacitor across the output. Pulse-testing techniques maintain  $T_J$  as close to  $T_A$  as possible. Thermal effects must be taken into account separately.



#### **Electrical Characteristics**

at specified virtual junction temperature,  $V_I$  = 17 V,  $I_O$  = 350 mA,  $T_J$  = 25°C (unless otherwise noted)

PARAMETER	TEST CONDITIONS(1)			μ <b>Α</b>	μ <b>Α78Μ10C</b>			
PARAMETER		MIN	TYP	MAX	UNIT			
Output voltage	$V_1 = 12.5 \text{ V to } 25 \text{ V},$	I − Ε mΛ to 2Ε0 mΛ		9.6	10	10.4	V	
Output voltage	$V_1 = 12.5 \text{ V to } 25 \text{ V},$	$I_O = 5 \text{ mA to } 350 \text{ mA}$	$T_J = 0$ °C to 125°C	9.5		10.5	V	
Input voltage regulation	1 200 mA	$V_I = 12.5 \text{ V to } 28 \text{ V}$			7	100	mV	
	I <sub>O</sub> = 200 mA	$V_{I} = 14 \text{ V to } 28 \text{ V}$			2	50	IIIV	
Pipple rejection	V <sub>I</sub> = 15 V to 25 V,	$I_{O} = 100 \text{ mA},$	$T_J = 0$ °C to 125°C	59			<b>ح</b>	
Ripple rejection	f = 120 Hz	I <sub>O</sub> = 300 mA		55	80		dB	
Output valta na na mulatia n	I <sub>O</sub> = 5 mA to 500 mA				25	200	mV	
Output voltage regulation	$I_O = 5$ mA to 200 mA				10	100	) 1117	
Temperature coefficient of output voltage	I <sub>O</sub> = 5 mA,	$T_J = 0$ °C to 125°C			-1		mV/°C	
Output noise voltage	f = 10 Hz to 100 kHz				64		μV	
Dropout voltage					2		V	
Bias current					4.7	6	mA	
Diag gurrant change	V <sub>I</sub> = 12.5 V to 28 V,	I <sub>O</sub> = 200 mA,	$T_J = 0$ °C to 125°C			8.0	mA	
Bias current change	$I_{O} = 5 \text{ mA to } 350 \text{ mA},$	$T_J = 0$ °C to 125°C				0.5	MA	
Short-circuit output current	V <sub>I</sub> = 35 V				245		mA	
Peak output current					0.7		Α	

<sup>(1)</sup> All characteristics are measured with a 0.33-μF capacitor across the input and a 0.1-μF capacitor across the output. Pulse-testing techniques maintain T<sub>J</sub> as close to T<sub>A</sub> as possible. Thermal effects must be taken into account separately.

#### **Electrical Characteristics**

at specified virtual junction temperature,  $V_I$  = 19 V,  $I_O$  = 350 mA,  $T_J$  = 25°C (unless otherwise noted)

PARAMETER	TEST CONDITIONS <sup>(1)</sup>			μΑ	μ <b>Α78M12C</b>		
PARAMETER	TEST CONDITIONS(**)				TYP	MAX	UNIT
Output voltage	$V_1 = 14.5 \text{ V to } 27 \text{ V},$	I − Ε mΛ to 2Ε0 mΛ		11.5	12	12.5	V
Output voltage	$V_1 = 14.5 \text{ V to } 27 \text{ V},$	$I_O = 5 \text{ mA to } 350 \text{ mA}$	$T_J = 0$ °C to 125°C	11.4		12.6	v
Input voltage regulation	1 200 m A	$V_1 = 14.5 \text{ V to } 30 \text{ V}$			8	100	mV
	I <sub>O</sub> = 200 mA	V <sub>I</sub> = 16 V to 30 V			2	50	IIIV
Dinale rejection	V <sub>I</sub> = 15 V to 25 V,	I <sub>O</sub> = 100 mA,	$T_J = 0$ °C to 125°C	55			dB
Ripple rejection	f = 120 Hz	I <sub>O</sub> = 300 mA		55	80		uБ
Output voltage regulation	I <sub>O</sub> = 5 mA to 500 mA				25	240	mV
	I <sub>O</sub> = 5 mA to 200 mA				10	120	1110
Temperature coefficient of output voltage	I <sub>O</sub> = 5 mA,	$T_J = 0^{\circ}\text{C} \text{ to } 125^{\circ}\text{C}$			-1		mV/°C
Output noise voltage	f = 10 Hz to 100 kHz				75		μV
Dropout voltage					2		V
Bias current					4.8	6	mA
Diag summent shapes	$V_I = 14.5 \text{ V to } 30 \text{ V},$	I <sub>O</sub> = 200 mA,	$T_J = 0$ °C to 125°C			8.0	A
Bias current change	$I_{O} = 5 \text{ mA to } 350 \text{ mA},$	$T_J = 0^{\circ}C$ to $125^{\circ}C$				0.5	mA
Short-circuit output current	V <sub>I</sub> = 35 V				240		mA
Peak output current					0.7		Α

<sup>(1)</sup> All characteristics are measured with a  $0.33-\mu F$  capacitor across the input and a  $0.1-\mu F$  capacitor across the output. Pulse-testing techniques maintain  $T_J$  as close to  $T_A$  as possible. Thermal effects must be taken into account separately.



The  $\mu$ A78M15 is obsolete and no longer supplied.

#### **Electrical Characteristics**

at specified virtual junction temperature,  $V_1 = 23 \text{ V}$ ,  $I_0 = 350 \text{ mA}$ ,  $T_J = 25^{\circ}\text{C}$  (unless otherwise noted)

DADAMETED		TEST CONDITIONS(1)	μ <b>Δ</b>	UNIT			
PARAMETER		MIN	TYP	MAX	UNII		
Output voltage	V <sub>I</sub> = 17.5 V to 30 V,	I <sub>O</sub> = 5 mA to 350 mA		14.4	15	15.6	V
Output voltage	V <sub>1</sub> = 17.5 V to 30 V,	10 = 3 IIIA to 330 IIIA	$T_J = 0$ °C to 125°C	14.25		15.75	V
Input voltage regulation	I - 200 mA	$V_1 = 17.5 \text{ V to } 30 \text{ V}$			10	100	mV
Input voltage regulation	I <sub>O</sub> = 200 mA	$V_1 = 20 \text{ V to } 30 \text{ V}$		3	50	IIIV	
Dipple rejection	$V_{I} = 18.5 \text{ V to } 28.5 \text{ V},$	$I_{O} = 100 \text{ mA},$	$T_J = 0$ °C to 125°C	54			dB
Ripple rejection	f = 120 Hz		I <sub>O</sub> = 300 mA				
Output voltage regulation	$I_O = 5$ mA to 500 mA				25	300	mV
Output voltage regulation	$I_O = 5$ mA to 200 mA				10	150	IIIV
Temperature coefficient of output voltage	I <sub>O</sub> = 5 mA,	$T_J = 0$ °C to 125°C			-1		mV/°C
Output noise voltage	f = 10 Hz to 100 kHz				90		μV
Dropout voltage					2		V
Bias current					4.8	6	mA
Diag current change	$V_I = 17.5 \text{ V to } 30 \text{ V},$	$I_{O} = 200 \text{ mA},$	$T_J = 0$ °C to 125°C			0.8	A
Bias current change	$I_O = 5$ mA to 350 mA,	$T_J = 0$ °C to 125°C				0.5	mA
Short-circuit output current	V <sub>I</sub> = 35 V				240		mA
Peak output current					0.7		Α

<sup>(1)</sup> All characteristics are measured with a  $0.33-\mu F$  capacitor across the input and a  $0.1-\mu F$  capacitor across the output. Pulse-testing techniques maintain  $T_J$  as close to  $T_A$  as possible. Thermal effects must be taken into account separately.



#### **PACKAGING INFORMATION**

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
UA78M05CDCY	ACTIVE	SOT-223	DCY	4	80	Green (RoHS & no Sb/Br)	CU SN	Level-2-260C-1 YEAR
UA78M05CDCYG3	ACTIVE	SOT-223	DCY	4	80	Green (RoHS & no Sb/Br)	CU SN	Level-2-260C-1 YEAR
UA78M05CDCYR	ACTIVE	SOT-223	DCY	4	2500	Green (RoHS & no Sb/Br)	CU SN	Level-2-260C-1 YEAR
UA78M05CDCYRG3	ACTIVE	SOT-223	DCY	4	2500	Green (RoHS & no Sb/Br)	CU SN	Level-2-260C-1 YEAR
UA78M05CKC	NRND	TO-220	KC	3	50	Pb-Free (RoHS)	CU SN	N / A for Pkg Type
UA78M05CKCS	ACTIVE	TO-220	KCS	3	50	Pb-Free (RoHS)	CU SN	N / A for Pkg Type
UA78M05CKCSE3	ACTIVE	TO-220	KCS	3	50	Pb-Free (RoHS)	CU SN	N / A for Pkg Type
UA78M05CKTPR	NRND	PFM	KTP	2	3000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM
UA78M05CKTPRG3	NRND	PFM	KTP	2	3000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM
UA78M05CKVURG3	ACTIVE	PFM	KVU	3	2500	Green (RoHS & no Sb/Br)	CU SN	Level-3-260C-168 HR
UA78M05IDCY	ACTIVE	SOT-223	DCY	4	80	Green (RoHS & no Sb/Br)	CU SN	Level-2-260C-1 YEAR
UA78M05IDCYG3	ACTIVE	SOT-223	DCY	4	80	Green (RoHS & no Sb/Br)	CU SN	Level-2-260C-1 YEAR
UA78M05IDCYR	ACTIVE	SOT-223	DCY	4	2500	Green (RoHS & no Sb/Br)	CU SN	Level-2-260C-1 YEAR
UA78M05IDCYRG3	ACTIVE	SOT-223	DCY	4	2500	Green (RoHS & no Sb/Br)	CU SN	Level-2-260C-1 YEAR
UA78M05IKC	NRND	TO-220	KC	3	50	Pb-Free (RoHS)	CU SN	N / A for Pkg Type
UA78M05IKCE3	NRND	TO-220	KC	3	50	Pb-Free (RoHS)	CU SN	N / A for Pkg Type
UA78M05IKCS	ACTIVE	TO-220	KCS	3	50	Pb-Free (RoHS)	CU SN	N / A for Pkg Type
UA78M05IKCSE3	ACTIVE	TO-220	KCS	3	50	Pb-Free (RoHS)	CU SN	N / A for Pkg Type
UA78M05IKTPR	NRND	PFM	KTP	2	3000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM
UA78M05IKTPRG3	NRND	PFM	KTP	2	3000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM
UA78M05IKVURG3	ACTIVE	PFM	KVU	3	2500	Green (RoHS & no Sb/Br)	CU SN	Level-3-260C-168 HR
UA78M06CKC	OBSOLETE	TO-220	KC	3		TBD	Call TI	Call TI
UA78M06CKTPR	NRND	PFM	KTP	2	3000	Green (RoHS & no Sb/Br)		Level-1-260C-UNLIM
UA78M06CKTPRG3	NRND	PFM	KTP	2	3000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM
UA78M06CKVURG3	ACTIVE	PFM	KVU	3	2500	Green (RoHS & no Sb/Br)	CU SN	Level-3-260C-168 HR





om 7-Jan-2008

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp (3)
UA78M08CDCY	ACTIVE	SOT-223	DCY	4	80	Green (RoHS & no Sb/Br)	CU SN	Level-2-260C-1 YEAR
UA78M08CDCYG3	ACTIVE	SOT-223	DCY	4	80	Green (RoHS & no Sb/Br)	CU SN	Level-2-260C-1 YEAR
UA78M08CDCYR	ACTIVE	SOT-223	DCY	4	2500	Green (RoHS & no Sb/Br)	CU SN	Level-2-260C-1 YEAR
UA78M08CDCYRG3	ACTIVE	SOT-223	DCY	4	2500	Green (RoHS & no Sb/Br)	CU SN	Level-2-260C-1 YEAR
UA78M08CKC	NRND	TO-220	KC	3	50	Pb-Free (RoHS)	CU SN	N / A for Pkg Type
UA78M08CKCE3	NRND	TO-220	KC	3	50	Pb-Free (RoHS)	CU SN	N / A for Pkg Type
UA78M08CKCS	ACTIVE	TO-220	KCS	3	50	Pb-Free (RoHS)	CU SN	N / A for Pkg Type
UA78M08CKCSE3	ACTIVE	TO-220	KCS	3	50	Pb-Free (RoHS)	CU SN	N / A for Pkg Type
UA78M08CKTPR	NRND	PFM	KTP	2	3000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM
UA78M08CKTPRG3	NRND	PFM	KTP	2	3000	TBD	Call TI	Call TI
UA78M08CKVURG3	ACTIVE	PFM	KVU	3	2500	Green (RoHS & no Sb/Br)	CU SN	Level-3-260C-168 HR
UA78M09CKC	OBSOLETE	TO-220	KC	3		TBD	Call TI	Call TI
UA78M09CKTP	OBSOLETE	PFM	KTP	2		TBD	Call TI	Call TI
UA78M09CKTPR	NRND	PFM	KTP	2	3000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM
UA78M09CKTPRG3	NRND	PFM	KTP	2	3000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM
UA78M09CKVURG3	ACTIVE	PFM	KVU	3	2500	Green (RoHS & no Sb/Br)	CU SN	Level-3-260C-168 HR
UA78M10CKC	OBSOLETE	TO-220	KC	3		TBD	Call TI	Call TI
UA78M10CKTPR	NRND	PFM	KTP	2	3000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM
UA78M10CKTPRG3	NRND	PFM	KTP	2	3000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM
UA78M10CKVURG3	ACTIVE	PFM	KVU	3	2500	Green (RoHS & no Sb/Br)	CU SN	Level-3-260C-168 HR
UA78M12CKC	NRND	TO-220	KC	3	50	Pb-Free (RoHS)	CU SN	N / A for Pkg Type
UA78M12CKCS	ACTIVE	TO-220	KCS	3	50	Pb-Free (RoHS)	CU SN	N / A for Pkg Type
UA78M12CKCSE3	ACTIVE	TO-220	KCS	3	50	Pb-Free (RoHS)	CU SN	N / A for Pkg Type
UA78M12CKTPR	NRND	PFM	KTP	2	3000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM
UA78M12CKTPRG3	NRND	PFM	KTP	2	3000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM
UA78M12CKVURG3	ACTIVE	PFM	KVU	3	2500	Green (RoHS & no Sb/Br)	CU SN	Level-3-260C-168 HR
UA78M33CDCY	ACTIVE	SOT-223	DCY	4	80	Green (RoHS & no Sb/Br)	CU SN	Level-2-260C-1 YEAF
UA78M33CDCYG3	ACTIVE	SOT-223	DCY	4	80	Green (RoHS &	CU SN	Level-2-260C-1 YEAF





om 7-Jan-2008

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
						no Sb/Br)		
UA78M33CDCYR	ACTIVE	SOT-223	DCY	4	2500	Green (RoHS & no Sb/Br)	CU SN	Level-2-260C-1 YEAR
UA78M33CDCYRG3	ACTIVE	SOT-223	DCY	4	2500	Green (RoHS & no Sb/Br)	CU SN	Level-2-260C-1 YEAR
UA78M33CKC	NRND	TO-220	KC	3	50	Pb-Free (RoHS)	CU SN	N / A for Pkg Type
UA78M33CKCE3	NRND	TO-220	KC	3	50	Pb-Free (RoHS)	CU SN	N / A for Pkg Type
UA78M33CKCS	ACTIVE	TO-220	KCS	3	50	Pb-Free (RoHS)	CU SN	N / A for Pkg Type
UA78M33CKCSE3	ACTIVE	TO-220	KCS	3	50	Pb-Free (RoHS)	CU SN	N / A for Pkg Type
UA78M33CKTPR	NRND	PFM	KTP	2	3000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM
UA78M33CKTPRG3	NRND	PFM	KTP	2	3000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM
UA78M33CKVURG3	ACTIVE	PFM	KVU	3	2500	Green (RoHS & no Sb/Br)	CU SN	Level-3-260C-168 HR

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

**Pb-Free** (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

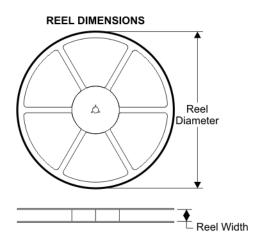
In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.





v.ti.com 5-Oct-2007

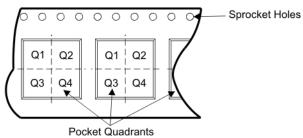
#### TAPE AND REEL BOX INFORMATION



# TAPE DIMENSIONS KO P1 BO W Cavity A0

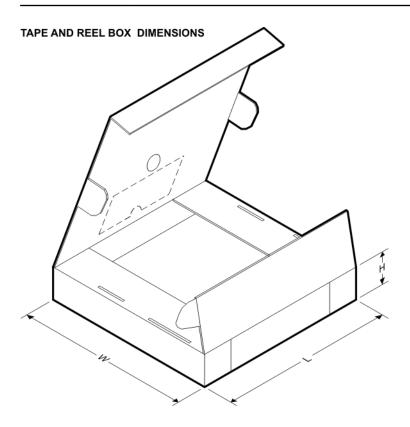
	Dimension designed to accommodate the component width
В	Dimension designed to accommodate the component length
	0 Dimension designed to accommodate the component thickness
V	Overall width of the carrier tape
ГР	Pitch between successive cavity centers

#### QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



Device	Package	Pins		Reel Diameter (mm)	Reel Width (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
UA78M05CKVURG3	KVU	3	SITE 45	330	16	6.9	10.5	2.7	8	16	Q2
UA78M05IKVURG3	KVU	3	SITE 45	330	16	6.9	10.5	2.7	8	16	Q2
UA78M06CKVURG3	KVU	3	SITE 45	330	16	6.9	10.5	2.7	8	16	Q2
UA78M08CKVURG3	KVU	3	SITE 45	330	16	6.9	10.5	2.7	8	16	Q2
UA78M09CKVURG3	KVU	3	SITE 45	330	16	6.9	10.5	2.7	8	16	Q2
UA78M10CKVURG3	KVU	3	SITE 45	330	16	6.9	10.5	2.7	8	16	Q2
UA78M12CKVURG3	KVU	3	SITE 45	330	16	6.9	10.5	2.7	8	16	Q2
UA78M33CKVURG3	KVU	3	SITE 45	330	16	6.9	10.5	2.7	8	16	Q2

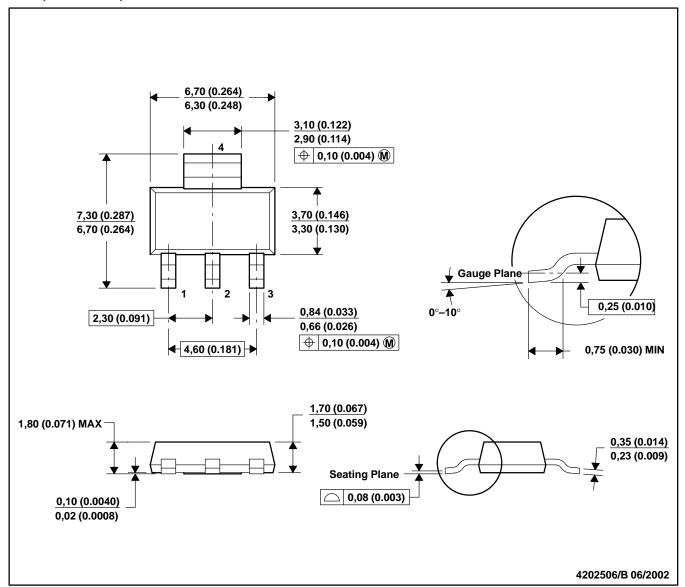




Device	Package	Pins	Site	Length (mm)	Width (mm)	Height (mm)
UA78M05CKVURG3	KVU	3	SITE 45	340.0	340.0	38.0
UA78M05IKVURG3	KVU	3	SITE 45	340.0	340.0	38.0
UA78M06CKVURG3	KVU	3	SITE 45	340.0	340.0	38.0
UA78M08CKVURG3	KVU	3	SITE 45	340.0	340.0	38.0
UA78M09CKVURG3	KVU	3	SITE 45	340.0	340.0	38.0
UA78M10CKVURG3	KVU	3	SITE 45	340.0	340.0	38.0
UA78M12CKVURG3	KVU	3	SITE 45	340.0	340.0	38.0
UA78M33CKVURG3	KVU	3	SITE 45	340.0	340.0	38.0

#### DCY (R-PDSO-G4)

#### **PLASTIC SMALL-OUTLINE**



NOTES: A. All linear dimensions are in millimeters (inches).

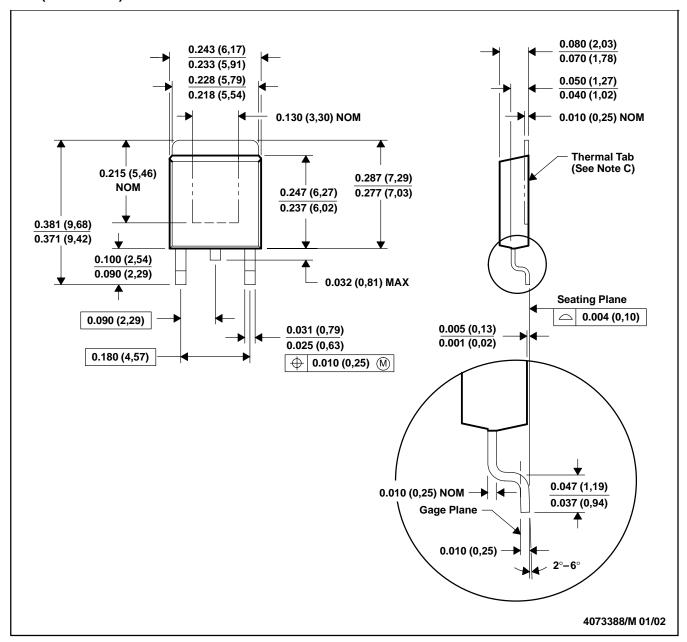
B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion.

D. Falls within JEDEC TO-261 Variation AA.

#### KTP (R-PSFM-G2)

#### PowerFLEX™ PLASTIC FLANGE-MOUNT PACKAGE



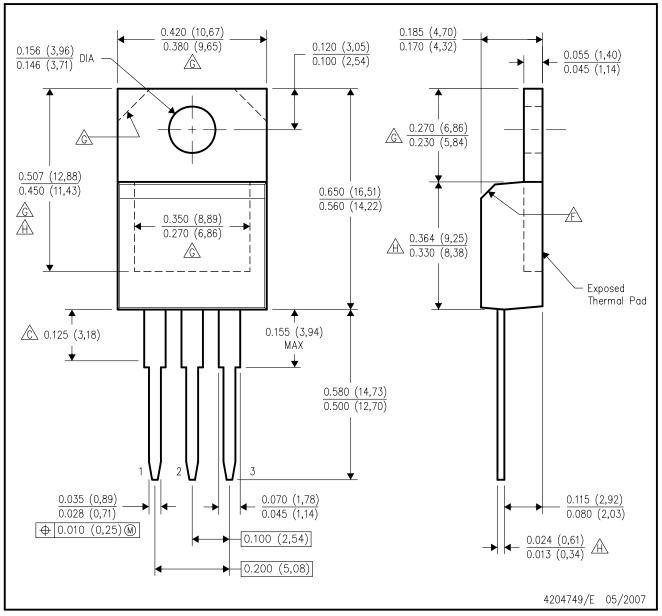
- NOTES: A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C. The center lead is in electrical contact with the thermal tab.
  - D. Dimensions do not include mold protrusions, not to exceed 0.006 (0,15).
  - E. Falls within JEDEC TO-252 variation AC.

PowerFLEX is a trademark of Texas Instruments.



## KCS (R-PSFM-T3)

#### PLASTIC FLANGE-MOUNT PACKAGE



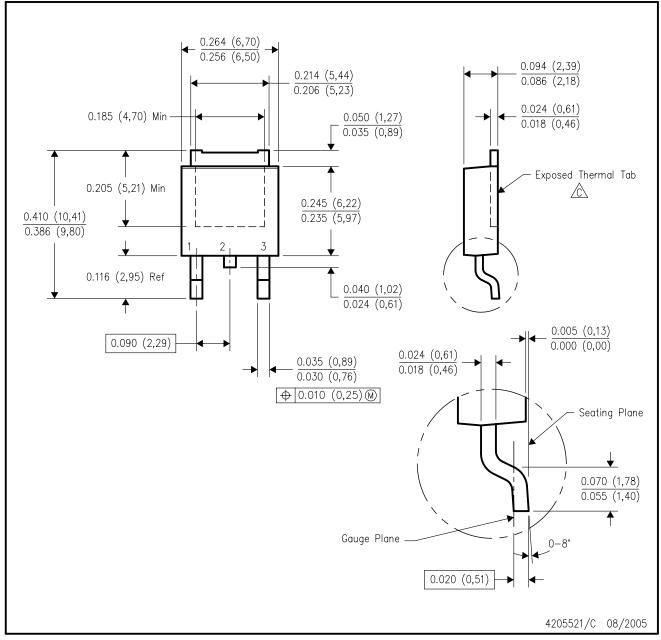
NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Lead dimensions are not controlled within this area.
- D. All lead dimensions apply before solder dip.
- E. The center lead is in electrical contact with the mounting tab.
- The chamfer is optional.
- Thermal pad contour optional within these dimensions.
- Falls within JEDEC TO-220 variation AB, except minimum lead thickness, minimum exposed pad length, and maximum body length.



# KVU (R-PSFM-G3)

### PLASTIC FLANGE-MOUNT PACKAGE



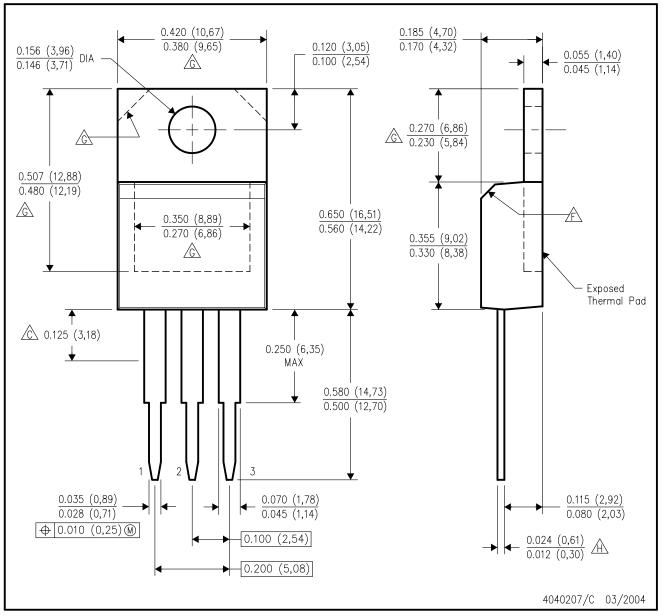
NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- The center lead is in electrical contact with the exposed thermal tab.
- D. Body Dimensions do not include mold flash or protrusions. Mold flash and protrusion shall not exceed 0.006 (0,15) per side.
- E. Falls within JEDEC TO-252 variation AA.



# KC (R-PSFM-T3)

#### PLASTIC FLANGE-MOUNT PACKAGE



NOTES: A

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Lead dimensions are not controlled within this area.
- D. All lead dimensions apply before solder dip.
- E. The center lead is in electrical contact with the mounting tab.
- The chamfer is optional.
- Thermal pad contour optional within these dimensions.
- Falls within JEDEC TO-220 variation AB, except minimum lead thickness.



#### **IMPORTANT NOTICE**

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, modifications, enhancements, improvements, and other changes to its products and services at any time and to discontinue any product or service without notice. Customers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All products are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its hardware products to the specifications applicable at the time of sale in accordance with TI's standard warranty. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by government requirements, testing of all parameters of each product is not necessarily performed.

TI assumes no liability for applications assistance or customer product design. Customers are responsible for their products and applications using TI components. To minimize the risks associated with customer products and applications, customers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any TI patent right, copyright, mask work right, or other TI intellectual property right relating to any combination, machine, or process in which TI products or services are used. Information published by TI regarding third-party products or services does not constitute a license from TI to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. Reproduction of this information with alteration is an unfair and deceptive business practice. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions

Resale of TI products or services with statements different from or beyond the parameters stated by TI for that product or service voids all express and any implied warranties for the associated TI product or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

TI products are not authorized for use in safety-critical applications (such as life support) where a failure of the TI product would reasonably be expected to cause severe personal injury or death, unless officers of the parties have executed an agreement specifically governing such use. Buyers represent that they have all necessary expertise in the safety and regulatory ramifications of their applications, and acknowledge and agree that they are solely responsible for all legal, regulatory and safety-related requirements concerning their products and any use of TI products in such safety-critical applications, notwithstanding any applications-related information or support that may be provided by TI. Further, Buyers must fully indemnify TI and its representatives against any damages arising out of the use of TI products in such safety-critical applications.

TI products are neither designed nor intended for use in military/aerospace applications or environments unless the TI products are specifically designated by TI as military-grade or "enhanced plastic." Only products designated by TI as military-grade meet military specifications. Buyers acknowledge and agree that any such use of TI products which TI has not designated as military-grade is solely at the Buyer's risk, and that they are solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI products are neither designed nor intended for use in automotive applications or environments unless the specific TI products are designated by TI as compliant with ISO/TS 16949 requirements. Buyers acknowledge and agree that, if they use any non-designated products in automotive applications, TI will not be responsible for any failure to meet such requirements.

Following are URLs where you can obtain information on other Texas Instruments products and application solutions:

#### **Products Amplifiers** amplifier.ti.com Data Converters dataconverter.ti.com DSP dsp.ti.com Clocks and Timers www.ti.com/clocks Interface interface.ti.com Logic logic.ti.com Power Mgmt power.ti.com microcontroller.ti.com Microcontrollers www.ti-rfid.com RF/IF and ZigBee® Solutions www.ti.com/lprf

Applications	
Audio	www.ti.com/audio
Automotive	www.ti.com/automotive
Broadband	www.ti.com/broadband
Digital Control	www.ti.com/digitalcontrol
Medical	www.ti.com/medical
Military	www.ti.com/military
Optical Networking	www.ti.com/opticalnetwork
Security	www.ti.com/security
Telephony	www.ti.com/telephony
Video & Imaging	www.ti.com/video
Wireless	www.ti.com/wireless

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265 Copyright 2008, Texas Instruments Incorporated